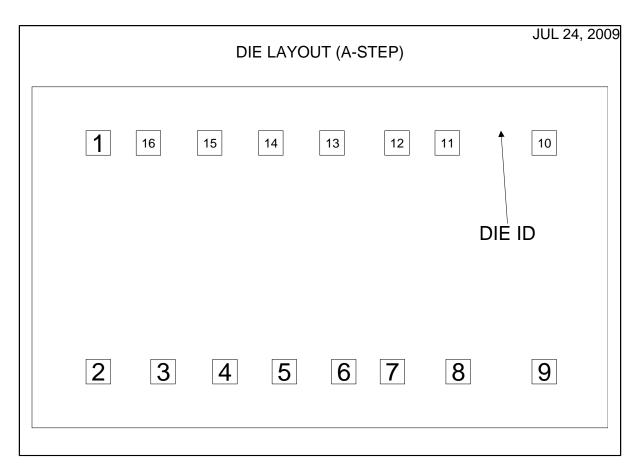


ADC128S102 MDP 8-Channel, 50 kSPS to 1 MSPS, 12-Bit A/D Converter



## DIE/WAFER CHARACTERISTICS

DIE/WAFER CHARA	CTERISTICS						
Fabrication Attributes		General Die Information					
Physical Die	ADC128HR	Bond Pad Opening	77.00µm x 77.00µm				
Identification		Size (min)					
Die Step	A	Bond Pad Metalization	AL 0.5%CU				
Physical Attributes		Passivation	PECVDOX NITRIDE				
Wafer Diameter	200mm	Back Side Metal	null				
Die Size (Drawn)	1808.48µm x 1071.88µm	Back Side Connection	Floating or GND				
	71.2mils x 42.2mils						
Thickness	304.8µm Nominal						
Min Pitch	153.00μm						
Note: All values are rounded to the nearest micron.							
Special Assembly Requirements:							



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Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		Χ	Υ	Χ		Υ
IN 4	1	-696	359	77	Х	7
IN 5	2	-696	-359	77	Х	7
IN 6	3	-493	-359	77	Х	7
IN 7	4	-299	-359	77	Х	7
DGND	5	-112	-359	77	Х	7
VD	6	75	-359	77	Х	7
DIN	7	228	-359	77	Х	7
DOUT	8	434	-359	77	Х	7
SCLK	9	704	-359	77	Х	7
/CS	10	704	359	77	Х	7
VA	11	400	359	77	Х	77
AGND	12	242	359	77	Х	77
IN 0	13	38	359	77	Х	7
IN 1	14	-154	359	77	х	77
IN 2	15	-347	359	77	Χ	77
IN 3	16	-539	359	77	Х	77



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